

SECURITY CODE		MITSUBISHI ELECTRIC CORPORATION					
SPEC.NAME Application Note	Prepared by	S.Iura	R E V				
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	DATE	Aug.26.2002					

Mounting Test Result (CM800DZ-34H)

In this application note we report on the test result of mounting for HVIGBT according to our recommended mounting procedure HPM-216-D.

1. Test conditions

- | | |
|----------------------------|-----------------------------------|
| (1) Flatness of base plate | X-axis: -10 μm, Y-axis: -20 μm |
| (2) Flatness of heatsink | ≤ 5 μm |
| (3) Thermal grease type | G-747 (Shinetsu Silicone) |
| (4) Thermal grease weight | 4.8 g (contains 100 μm thickness) |
| (5) Mounting torque | 3 N·m |

2. Test results

The area with no contact in the center of module was not observed in the above test conditions. The following pictures are ;

- | | |
|---------------------------|--------|
| (1) Initial of base plate | Fig. 1 |
| (2) Base plate | Fig. 2 |
| (3) Heatsink | Fig. 3 |

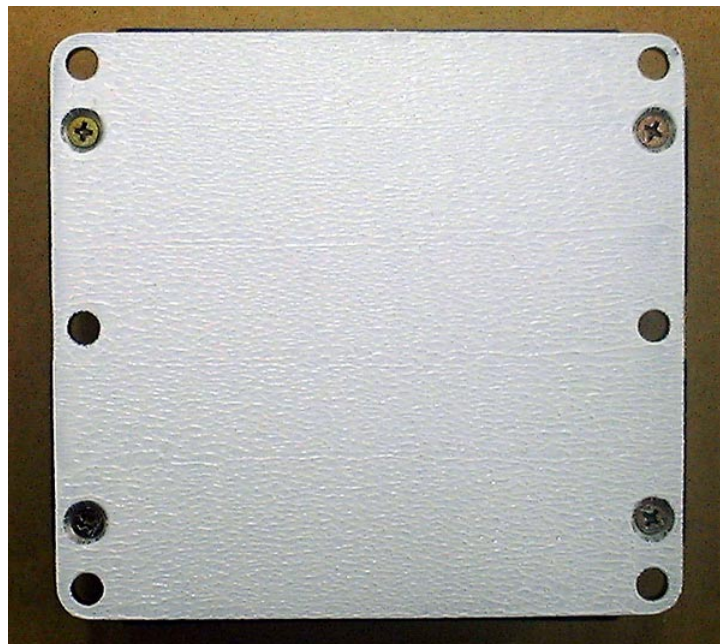


Fig. 1

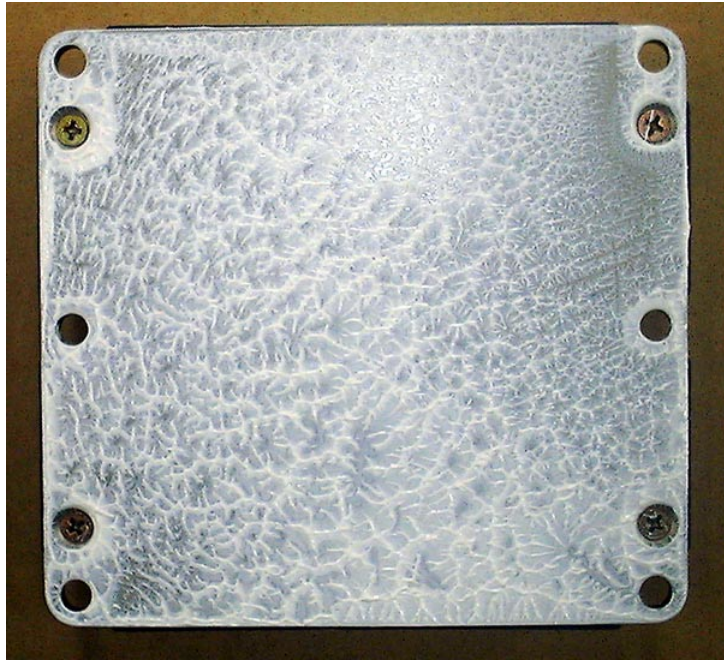


Fig. 2

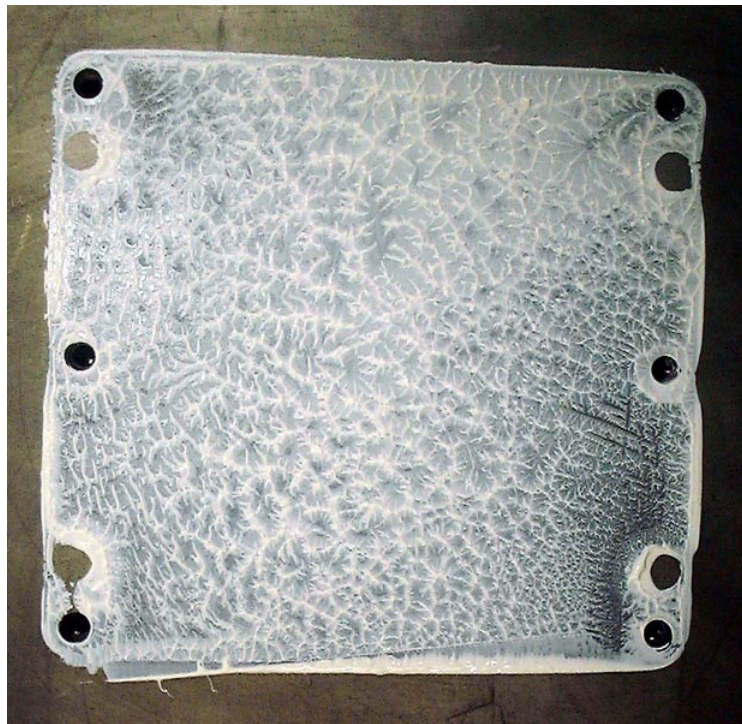


Fig. 3